Atmel®				MICRO	HIP
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
		● ATMEL  XXXXXXXXX  XXXX-X  YYWW  AAAAAA	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Class, Die Revision, Assembly Location Code Line 4 = Date Code Line 5 = Lot Traceability  ● = Pin 1 indicator	• ATMEL  XXXXXXX  XX-COO  YYWWNNN	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Class, Die Revision, Country of Origin Line 4 = Lot Traceability  ■ = Pin 1 indicator
		ATMEL  XXXXXXXX  XXXXYYWW#  XXXX-X  XXXXXXX  AAAAAA	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) Line 4 = Class, Assembly Location Code Line 5 = Die ID, Revision Line 6 = Lot Traceability ● = Pin 1 indicator	• AMEL  XXXXXXX  XXX-COO  XXXXXX  YYWWNNN	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability  ■ = Pin 1 indicator
24 / 32 / 40 / 44 / 48	VQFN 5X5 MM	XXXXXX XXXXXX AAAAAA X YYWW	Top Mark Line 1= Device Name Line 2 = Device Information Line 3 = Lot Traceability Line 4 = Subcon Code, Date Code  ● = Pin 1 indicator	● XXXXXX XXXXXX YYWWNNN CC YYWW	Top Mark Line 1= Device Name Line 2 = Device Information Line 3 = Lot Traceability Line 4 = Country of Origin, Date Code  ■ = Pin 1 indicator
		•XXXXXXXX AAAAAA.# X YYWW	Top Mark Line 1= Device Name Line 2 = Lot Traceability Line 3 = Date Code	● XXXXXXXX YYWWNNN CCYYWW	Top Mark Line 1= Device Name Line 2 = Lot Traceability Line 3 = Country of Origin, Date Code
		● ATMEL  XXXXXXXX  XXXXXXX  XXXXXX  YYWW#-X  AAAAAA  OR  ATMEL  XXXXXXXX  XXXX  XXX  XXX  AAAAAA	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, MRL (if shown in ABI) Line 5 = Lot Traceability  ■ = Pin 1 indicator	● ATMEL  XXXXXX  XX-COO  XXXXXX  YYWWNNN  OR  ATMEL  XXXXXX  XXXXXX  XXXXXX  YYWWNNN	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability  ■ = Pin 1 indicator

		Atmel		MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)	
		• ATMEL XXXXXXXXX XXXX-X YYWW AAAAAA	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, MRL (if shown in ABI) Line 4 = Date Code Line 5 = Lot Traceability  ■ = Pin 1 indicator	• ATMEL XXXXXXX XX-COO YYWWNNN	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability  ■ = Pin 1 indicator	
40	VQFN 6X6 MM	● ATMEL  XXXXXXXXX  XXXX-X  YYWW  AAAAAA	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code Line 5 = Lot Traceability  ● = Pin 1 indicator	• ATMEL  XXXXXXX  XX-COO  YYWWNNN	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability  ■ = Pin 1 indicator	
48	VQFN 6X6 MM	<pre> /tmel  xxxxxxx  xxxxxx  yywwx x  AAAAAA  ARM  </pre>	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM  ■ = Pin 1 indicator	<pre> /Itmel xxxxxxx xxxxxx yyww x yyww x yywwnnn ARM </pre>	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM  ■ = Pin 1 indicator	
		• ATMEL  XXXXXXXXX  XXXX-X  YYWW  AAAAAA	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code Line 5 = Lot Traceability  ● = Pin 1 indicator	• ATMEL XXXXXXX XX-COO YYWWNNN	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability  ■ = Pin 1 indicator	

Atmel				MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)	
44 / 64	VQFN 7X7 MM	● ATMEL  XXXXXXXX  XXXXYYWW#  XXXX-X  XXXXXX  AAAAAA	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) Line 4 = Country of Assembly, Assembly Location Code Line 5 = Die ID, Revision Line 6 = Lot Traceability  ● = Pin 1 indicator	• AMEL  XXXXXXX  XXX-COO  XXXXXX  YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability  ■ = Pin 1 indicator  Bottom Mark No bottom mark	
48	VQFN 7X7 MM	Atmel  XXXXXXXXX  XX  YYWWX X  AAAAAA ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM	Atmel  XXXXXXXXX  XX  YYWW X  YYWWNNN ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM  ■ = Pin 1 indicator	
64	VQFN 7.5X7.5 MM	LIMES  XXXXXXXXXX  YYWWX X  AAAAAA	Top Mark Line 1= LIMES Line 2 = Device Name Line 3 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability	LIMES  XXXXXXXXXX  YYWW X  YYWWNNN	Top Mark Line 1= LIMES Line 2 = Device Name Line 3 = Date Code, Design Revision Line 5 = Lot Traceability  ■ = Pin 1 indicator	
		XXXXXXXXXXXX  YYWWX X  AAAAAA	Top Mark Line 1= Device Name Line 2 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability  ● = Pin 1 indicator	XXXXXXXXXXXX  YYWW X  YYWWNNN	Top Mark Line 1= Device Name Line 2 = Date Code, Design Revision Line 5 = Lot Traceability  ■ = Pin 1 indicator	

		Atmel	MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
		Atmel  XXXXXXXXXXX  XX  YYWWX X  AAAAAA ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM  ● = Pin 1 indicator	Atmel  XXXXXXXXXX  XX  YYWW X  YYWWNNN ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM  ■ = Pin 1 indicator
64	VQFN 9X9 MM	Atmel  XXXXXXXXXXXX  XX  YYWWX X  AAAAAA ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM	Atmel  XXXXXXXXXXX  XX  YYWW X  YYWWNNN ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM  ■ = Pin 1 indicator
		ATMEL  XXXXXXXX  XXXXYYWW#  XXXX-X  XXXXXXX  AAAAAA	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) Line 4 = Country of Assembly, Assembly Location Code Line 5 = Die ID, Revision Line 6 = Lot Traceability  ■ = Pin 1 indicator	• AMEL  XXXXXXX  XXX - COO  XXXXXXX  YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability  ■ = Pin 1 indicator  Bottom Mark No bottom mark
		● ATMEL  XXXXXXXXX  XXXX-X  YYWW  AAAAAA	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Class, Die Revision, Assembly Location Code Line 4 = Date Code Line 5 = Lot Traceability  ● = Pin 1 indicator	• ATMEL  XXXXXXX  XX-COO  YYWWNNN	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Class, Die Revision, Country of Origin Line 4 = Lot Traceability  ■ = Pin 1 indicator

		Atmel	MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
20	WQFN 4X4 MM	• XYYWW# XXXXXX XXXXXX AAAAA	Top Mark Line 1= A, Date Code, MRL (if shown in ABI) Line 2 = Device Name (shortened) Line 3 = Device Information Line 4 = Lot Traceability  ■ = Pin 1 indicator	ATMEL XXXXX XXXX-COO YYWWNNN	Top Mark Line 1= ATMEL Line 2 = Device Name (shortened) Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability  ■ = Pin 1 indicator
8	UDQFN 2X2 MM	• XXX XXX YZZ	Top Mark Line 1= Device Name (shortened) Line 2 = Device type code / Class code / Die Revision / Assembly location code Line 3 = Lot Traceability  ■ = Pin 1 indicator	• XXX XXX NNN	Top Mark Line 1= Device Name (shortened) Line 2 = Device type code / Class code, Die Revision / Assembly location code Line 3 = Lot Traceability  ■ = Pin 1 indicator
8	UDFN 2X3 MM	XXX XXX YTC	Top Mark Line 1= Truncation Code Line 2 = Device Information Line 3 = Lot Traceability  ■ = Pin 1 indicator	XXX XXX NNN	Top Mark Line 1= Truncation Code Line 2 = Device Information Line 3 = Lot Traceability  ■ = Pin 1 indicator
		YM TC C	Top Mark Line 1= Year, Month Line 2 = Lot Traceability Line 3 = Subcon Code	YWW NNN CC	Top Mark Line 1= Date Code Line 2 = Lot Traceability Line 3 = Country Code
8	XDFN / UDFN	C YM TC	Top Mark Line 1= Subcon Code Line 2 = Year, Month Line 3 = Lot Traceability	CC YWW NNN	Top Mark Line 1= Country of Origin Line 2 = Date Code Line 3 = Lot Traceability

		Atmel	MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
8	UDFN 6X5 MM	XXXXXXXX XXXXXXXX •AAAAAA	Top Mark Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code Line 3 = Lot Traceability  ■ = Pin 1 indicator	XXXXXXXX XXXXXXXX •YYWWNNN	Top Mark Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code Line 3 = Lot Traceability  ■ = Pin 1 indicator
10	VDFN 3X3 MM	• XXX XXX YZZ	Top Mark Line 1= Device Name (shortened) Line 2 = Device type code / Class code / Die Revision / Assembly location code Line 3 = Lot Traceability  ● = Pin 1 indicator	• XXX XXX WNNN	Top Mark Line 1= Device Name (shortened) Line 2 = Device type code / Class code, Die Revision / Assembly location code Line 3 = Lot Traceability
2	XSFN (DFN 5X3.5 MM)	XXXXX XXXXX YMTC	Top Mark Line 1= ATML Line 2 = Truncation Code, Device Information Line 3 = Lot Traceability  ● = Pin 1 indicator	XXXXX XXXXX WWNNN	Top Mark Line 1= ATML Line 2 = Truncation Code, Device Information, Year Line 3 = Lot Traceability  ■ = Pin 1 indicator
3	LAB (DFN 2.5X6.5 MM)	C YM TC	Top Mark Line 1= Subcon Code Line 2 = Year, Month Line 3 = Trace Code  ● = Pin 1 indicator	● XX YWW NNN	Top Mark Line 1= Country of Origin Line 2 = Date Code Line 3 = Lot Traceability

	Atmel			MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)	
20	PLCC	XXXXXXXX AAAAA XXXXXXXXX	Top Mark Line 1= Device Name Line 2 = Lot Traceability Line 3 = Device Information, Date Code  ● = Pin 1 indicator	XXXXXXXXX XXXXXXXXX YYWWNNN CC	Top Mark Line 1= Device Name Line 2 = Device Information, Date Code Line 3 = Lot Traceability Line 4 = Country of Origin  ■ = Pin 1 indicator	
		XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI)  ▲ = Pin 1 location  Bottom Mark Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability	XXXXXXXXX XXXX-COO YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability	
28	PLCC	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Lot Traceability O = Pin 1 indicator  Bottom Mark Line 1 = Country Code Country of Origin in injector mold Line 2 = Lot Traceability	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark Country of Origin in injector mold	
		YYWW AAAAAAA	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Lot Traceability O = Pin 1 indicator  Bottom Mark Line 1 = Country Code Country of Origin in injector mold Line 2 = Lot Traceability	XXXXXXXXXXX YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark Country of Origin in injector mold	

		Atmel	MICROC	HIP	
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
		XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI)  ▲ = Pin 1 location  Bottom Mark Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability	XXXXXXXXXX XXXX-COO YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability
32	PLCC	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, MRL (if shown in ABI)   ■ = Pin 1 location  Bottom Mark Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability	XXXXXXXXX XXX-XXXXXX YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Die ID, Revision Line 4 = Lot Traceability
44	PLCC	CC  XXXXXXXXXXX  YYWW AAAAAAA	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Lot Traceability O = Pin 1 indicator  Bottom Mark Line 1 = Country Code Country of Origin in injector mold Line 2 = Lot Traceability	YYWWNNN O	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark Country of Origin in injector mold

		Atmel	MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
		CC  XXXXXXXXXXX  XYWW AAAAAA  AAAAAA	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Lot Traceability O = Pin 1 indicator  Bottom Mark Line 1 = Country Code Country of Origin in injector mold Line 2 = Lot Traceability		Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark Country of Origin in injector mold
		EDR  XXXXXXXXXXX  XXXXXXXXXX  YYWW AAAAAAA	Top Mark Line 1= Atmel Logo, EDR Line 2 = Silicon Revision Line 3 = Device Name Line 4 = Date Code, Lot Traceability O = Pin 1 indicator  Bottom Mark Line 1 = Country Code Country of Origin in injector mold Line 2 = Lot Traceability	EDR  XXXXXXXXXXX  XXXXXXXXXX  YYWWNNN	Top Mark Line 1= Atmel Logo, EDR Line 2 = Silicon Revision Line 3 = Device Name Line 4 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark Country of Origin in injector mold
		XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, MRL (if shown in ABI)  ▲ = Pin 1 location  Bottom Mark Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability	XXXXXXXXX XXXX-COO YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country or Origin Line 4 = Lot Traceability

Atmel				MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)	
		XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, MRL (if shown in ABI)  = Pin 1 location Bottom Mark Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability	XXXXXXXXXX XXX-XXXXXX YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Die ID, Revision Line 4 = Lot Traceability	
52	PLCC	CC  XXXXXXXXXXX  YYWW AAAAAA	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Lot Traceability O = Pin 1 indicator  Bottom Mark Line 1 = Country Code Country of Origin in injector mold Line 2 = Lot Traceability	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark Country of Origin in injector mold	
		CC  XXXXXXXXXXX  XXXXXXXXXX  YYWW AAAAAA	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Lot Traceability O = Pin 1 indicator  Bottom Mark Line 1 = Country Code Country of Origin in injector mold Line 2 = Lot Traceability	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark Country of Origin in injector mold	

	Atmel			MICROC	HIP
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
84	PLCC	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, MRL (if shown in ABI)  ■ = Pin 1 location  Bottom Mark Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability	XXXXXXXXX XXXX-COO YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country or Origin Line 4 = Lot Traceability  Bottom Mark No bottom mark Country of Origin in injector mold
2	CONTACT (SIP MODULE - 4x2 MM)	X YM TC	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Lot Traceability O = Pin 1 indicator  Bottom Mark Line 1 = Country Code Country of Origin in injector mold Line 2 = Lot Traceability	• XX YWW NNN	Top Mark Line 1=Country of Origin Line 2 = Date Code Line 3 = Lot Traceability
8	MSOP - 3x3 MM	XXXXX XXXTC YWWX	Top Mark Line 1= Truncation Code Line 2 = Class Code, Trace Code Line 3 = Lot Traceability  ■ = Pin 1 indicator	XXXXX XXNNN YYWW	Top Mark Line 1= Truncation Code Line 2 = Class Code, Lot Traceability Line 3 = Date Code  ● = Pin 1 indicator
32 / 48	LQFP	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Lot Traceability O = Pin 1 indicator  Bottom Mark Line 1 = Country Code Line 2 = Lot Traceability	XXXXXXXXXX XXXXXXXXXX YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark

	Atmel			MICROC MICROC	HIP
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
		Atmel  XXXXXXXXXX  XX  YYWWX  AAAAAA	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark	Atmel  XXXXXXXXXX  XX  YYWW X  YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark
48	LQFP 7X7 MM	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI)  ▲ = Pin 1 location  Bottom Mark Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability	OAMEL  XXXXXXXXXX  XXXX-COO  XXXXXX  YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark
		Atmel  XXXXXXXXX  XXXXXXXX  YYWWX X  AAAAAA ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark	Atmel  XXXXXXXXXX  XXXXXXXX  YYWW X  YYWWNNNARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark
44	LQFP 10X10 MM	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI)   ■ Pin 1 location  Bottom Mark Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark

		Atmel	MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)  Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability  O = Pin 1 indicator  Bottom Mark No bottom mark
		XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Lot Traceability  ■ = Pin 1 indicator  Bottom Mark Line 1 = Country Code Line 2 = Lot Traceability	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	
64	LQFP 10X10 MM	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Lot Traceability	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability  ●O = Pin 1 indicator  Bottom Mark No bottom mark
		XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Lot Traceability O = Pin 1 indicator  Bottom Mark Line 1 = Country Code Line 2 = Lot Traceability	XXXXXXXXXX XXXXXXXXXX YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark
		XXXXXXXXXX XXXXXXXXXX YYWW AAAAA	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Lot Traceability O = Pin 1 indicator  Bottom Mark Line 1 = Country Code Line 2 = Lot Traceability	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark

		Atmel	MICROCHIP		
Lead/Pin/ Bump Count	Bump Package Pre-Change_Marking Diagram		Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
		Atmel  XXXXXXXXXXX  XXXXXXX  YYWWX X  AAAAAA ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark	Atmel  XXXXXXXXXXX  XXXXXXX  YYWW X  YYWWNNN ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark
80	LQFP 12X12 MM	Atmel  XXXXXXX  XXX  YYWWX X  AAAAAA	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision  Line 5 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark	Atmel  XXXXXXX  XXX  YYWW X  YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark
100	LQFP 14X14 MM	O AMEL  XXXXXXXXXXXX  YYWW AAAAA  CC  AAAAAA	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Lot Traceability O = Pin 1 indicator  Bottom Mark Line 1 = Country Code Line 2 = Lot Traceability	O AMEL  XXXXXXXXXXX  YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark
		MICROCHIP XXXXXXXXXX XXXXXX YYWWX X AAAAAA ARM	Top Mark Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision  Line 5 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark	MICROCHIP XXXXXXXXXX XXXXXX YYWW X YYWWNNN ARM	Top Mark Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark

		Atmel	MICROC	HIP	
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
		Atmel  XXXXXXXXXXXX  XXXXXXX  YYWWX  AAAAAA  ARM	Top Mark Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision  Line 5 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark	Atmel  XXXXXXXXXXX  XXXXXXX  YYWW X  YYWWNNN ARM	Top Mark Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark
		Atmel  XXXXXXXXXXX  XX  YYWWX-X X  AAAAAA ARM	OR Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision  Line 5 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark	Atmel  XXXXXXXXXXX  XX  YYWW-X X  YYWWNNN ARM	OR Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark
128	LQFP 14X20 MM	Atmel  XXXXXXXXXXX  XX  YYWWX  AAAAAA  ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision  Line 5 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark	Atmel  XXXXXXXXXXXX  XX  YYWW X  YYWWNNN ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark
144	LQFP 20X20 MM	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Lot Traceability O = Pin 1 indicator  Bottom Mark Line 1 = Country Code Line 2 = Lot Traceability	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark

		Atmel	MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
		MICROCHIP XXXXXXXXXX XXXXXXX YYWWX X AAAAAA ARM	Top Mark Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision  Line 5 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark	MICROCHIP XXXXXXXXXX XXXXXXX YYWW X YYWWNNN ARM	Top Mark Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark
		Atmel  XXXXXXXXXXXXXX  YYWWX X  AAAAAA ARM  O	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision  Line 5 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark	Atmel  XXXXXXXXXXXXXX  YYWW X  YYWWNNN ARM  O	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark
		Atmel  XXXXXXXXXX  XXXXXXX  YYWWX  AAAAAA  ARM  O	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision  Line 5 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark	Atmel  XXXXXXXXXX  XXXXXXX  YYWW  YYWWWNNN ARM  O	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark
176	LQFP 24X24 MM	MICROCHIP XXXXXXXXXXX XXXXXXX YYWWX X AAAAAA ARM	Top Mark Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision  Line 5 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark	MICROCHIP XXXXXXXXXXX XXXXXXX YYWW X YYWWNNN ARM	Top Mark Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark

		Atmel	MICROC	HIP	
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)  Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision  Line 5 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)  Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark
		Atmel  XXXXXXXXXX  XXXXX  YYWWX-X X  AAAAAA ARM  O		Atmel  XXXXXXXXXX  XXXXX  YYWW-X  YYWWNNNARM	
		Atmel  XXXXXXXXX  YYWWX X  AAAAAA  ARM  O	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Subcon Code, Design Revision  Line 4 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark	Atmel  XXXXXXXXX  YYWW X  YYWWNNN ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Design Revision Line 4 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark
100	PQFP 14X20 MM	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) O = Pin 1 indicator  ▲ = Pin 1 location  Bottom Mark Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark
208	PQFP 28X28 MM	Atmel  XXXXXXXXXXXX  XX  YYWWX X  AAAAAA ARM  O	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 3 = Date Code, Subcon Code, Design Revision Line 4 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark	Atmel  XXX  YYWW X  YYWWNNN ARM  O	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 3 = Date Code, Design Revision Line 4 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark

		Atmel	MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
32 / 48	TQFP 7X7 MM	XXXXXXXXXX XXXXXXXXXXX YYWW AAAAA	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Lot Traceability O = Pin 1 indicator  Bottom Mark Line 1 = Country Code Line 2 = Lot Traceability	XXXXXXXXXX XXXXXXXXXX YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark
		Atmel  XXXXXXXXXX  XX  YYWWX  AAAAAAA	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision  Line 5 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark	Atmel  XXXXXXXXXXX  XX  YYWW X  YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark
		Atmel  XXXXXXXXX  XXXXXXXX  YYWWX X  AAAAAA ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision  Line 5 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mark	Atmel  XXXXXXXXX  XXXXXXXX  YYWW X  YYWWNNNARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator  Bottom Mark No bottom mar
		ATMEL  XXXXXXXX  AU YYWWX  AAAAAA	Top Mark Line 1= Atmel Line 2 = Device Name Line 3 = Device Information, Date Code, Subcon Code Line 4 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark	ATMEL XXXXXXXX AU YYWW YYWWNNN	Top Mark Line 1= Atmel Line 2 = Device Name Line 3 = Device Information, Date Code Line 4 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark

		Atmel	MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
		SINOWELL XXXXXXXX XAUYYWWX AAAAAA	Top Mark Line 1= SINOWEL Line 2 = Device Name Line 3 = Device Information, Date Code, Subcon Code Line 4 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark	SINOWELL XXXXXXX XAUYYWW YYWWNNN	Top Mark Line 1= SINOWEL Line 2 = Device Name Line 3 = Device Information, Date Code Line 4 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark
		XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI)  ▲ = Pin 1 location  Bottom Mark Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability	XXXXXXXXX XXXX-COO XXXXXX YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark
44	TQFP 10X10 MM	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) O = Pin 1 indicator  ■ = Pin 1 location  Bottom Mark Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark
		XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI)   ■ = Pin 1 location  Bottom Mark Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability	O AMEL  XXXXXXXXXX  XXXX-COO  XXXXXX  YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark

		Atmel	MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)  Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark
Count		XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Lot Traceability O = Pin 1 indicator  Bottom Mark Line 1 = Country Code Line 2 = Lot Traceability	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	
64	TQFP 10X10 MM	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Lot Traceability  ■ = Pin 1 indicator  Bottom Mark Line 1 = Country Code Line 2 = Lot Traceability	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability  O = Pin 1 indicator  Bottom Mark No bottom mark
64	TQFP 14X14 MM	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI)   ■ Pin 1 location  Bottom Mark Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability	×XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark
		XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI)   ■ Pin 1 location  Bottom Mark Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability	OMEL  XXXXXXXXX  XXXX-COO  XXXXXX  YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark

		Atmel	MICROCHIP		
Lead/Pin/ Bump Count	Package Description TQFP 14X14 MM	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
100		XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI)	O AMEL  XXXXXXXXXX  XXXX-COO  YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark
		XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI)  ■ Pin 1 location  Bottom Mark Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability	O AMEL  XXXXXXXXXX  XXXX-COO  XXXXXX  YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark
		XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI)  ▲ = Pin 1 location  Bottom Mark Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability	O ANEL  XXXXXXXXXX  XXXX-COO  XXXXXX  YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability O = Pin 1 indicator  Bottom Mark No bottom mark

	Atmel				MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Markin	ng Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Markin	ng Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
		O AMEL  XXXXXXXXXXXX  YYWW AAAAA	CC AAAAAA	Top Mark Line 1= Atmel Logo Line 2 = Date Code, Lot Traceability O = Pin 1 indicator  Bottom Mark Line 1 = Country Code Line 2 = Lot Traceability	O MEL  XXXXXXXXXXX  YYWWNNN		Top Mark Line 1= Atmel Logo Line 2 = Lot Traceability O = Pin 1 indicator  Bottom Mark Line 1 = Country Code Line 2 = Lot Traceability